

PCN N° 2024-152-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Frame design optimization for EconoDUAL[™]3 – Product scope 2

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2025-01-27
- Infineon aligns with the widely recognized JEDEC STANDARD "JESD46", which stipulates:
 "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

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Management Board Jochen Hanebeck (CEO), Elke Reichart, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg Registered office Neubiberg Commercial register Amtsgericht München HRB 126492



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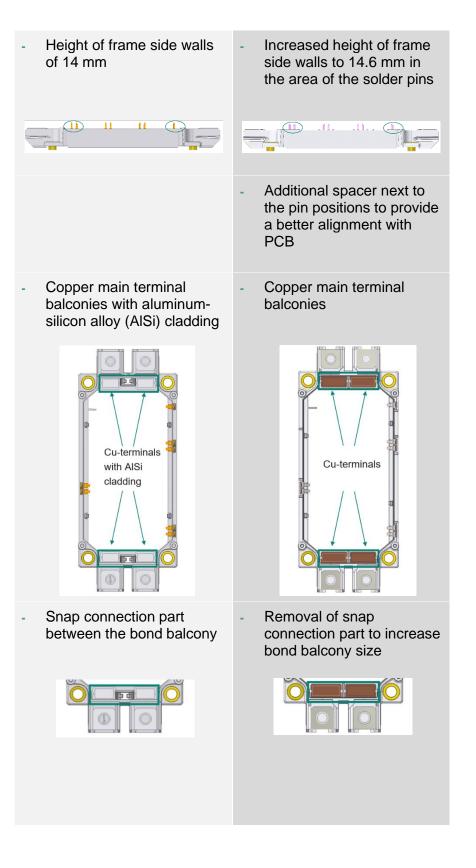
		Please refer to attached affected product list	
-	Products affected	PCN_2024-152-A_[customer-no].pdf	

Detailed change information

Subject	t Introduction of optimized EconoDUAL™3 frame design.				
Reason	Standardization of the frame for EconoDUAL™3 product port based on an optimized design.				
Description	<u>Old</u>	New			
		 Creepage and clearance stated according to IEC 60664-1, Ed. 3.0 			
	 d_{Creep,nom}, terminal to terminal = 13.0 mm 	 d_{Creep,nom}, terminal to terminal > 19.3 mm d_{Creep,min}, terminal to terminal = 19.3 mm 			
	 d_{Creep,nom}, terminal to heatsink = 14.5 mm 	 d_{Creep,nom}, terminal to baseplate > 15.0 mm d_{Creep,min}, terminal to baseplate = 14.7 mm 			
	 d_{Clear,nom}, terminal to terminal = 10.0 mm 	 d_{Clear,nom}, terminal to terminal > 10.0 mm d_{Clear,min}, terminal to terminal = 9.6 mm 			
	 d_{Clear,nom}, terminal to heatsink = 12.5 mm 	 d_{Clear,nom}, terminal to baseplate > 12.5 mm d_{Clear,min}, terminal to baseplate = 12.5 mm 			



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	 Addition of plastic bar between the bond balconies to enable sufficient spacing Filled with gel
- Aluminium bond wires for the main terminal connection	 Introduction of copper for the main terminal connection Due to the much higher conductivity of copper, the amount of bond wires is adjusted accordingly
	- Due to change of the bond wire and the bond balcony the MCDS will be adapted after the implementation



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-	Product identification	Individual production lot number and date code.	
 Impact of change 		Based on the qualification performed, no negative impact on quality, function and reliability exists. The assessment of the implementation of the optimizied frame design can be executed based on a 3D model, which can be provided on request. Datasheets will be updated after the implementation. No change in the SP ordering number.	
-	Attachments	PCN_2024-152-A_[<i>customer-no</i>].pdf 2_cip24152_A	affected product list qualification Report
	Time schedule		
	- Final qualification report	available	
	- First samples available	On request	

- Intended start of delivery 2025-05-01 or earlier, depending on customer acceptance. During changeover, a mixed delivery might happen.

If you have any questions, please do not hesitate to contact your local sales office.